



#### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	-40	V
Gate-Source Voltage (		(Note 5)	V <sub>GS</sub>	±20	V
		(Notes 9 & 11)		-5.2	
Continuous Drain Current	V <sub>GS</sub> = 10V	$T_A = +70^{\circ}C \text{ (Notes 7 & 9)}$	I <sub>D</sub>	-4.2	Α
		(Notes 6 & 9)		-4.0	]
Pulsed Drain Current	$V_{GS} = 10V$	(Notes 8 & 9)	I <sub>DM</sub>	-20.0	Α
Continuous Source Current (Body Diode)		(Notes 7 & 9)	Is	-3.2	Α
Pulsed Source Current (Body Diode) (Notes 8 &		(Notes 8 & 9)	I <sub>SM</sub>	-20.0	А

## Thermal Characteristics ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

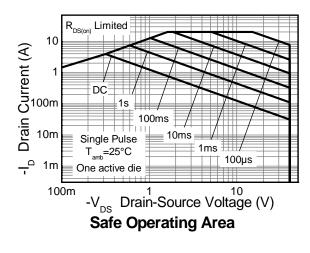
Characteristic		Symbol	Value	Unit	
	(Notes 6 & 9)		1.25 10.0		
Power dissipation Linear derating factor	(Notes 6 & 10)	P <sub>D</sub>	1.8 14.3	W mW/°C	
	(Notes 7 & 9)		2.14 17.2		
	(Notes 6 & 9)		100		
Thermal Resistance, Junction to Ambient	(Notes 6 & 10)	R <sub>0JA</sub>	70	00.004	
	(Notes 7 & 9)		58	°C/W	
Thermal Resistance, Junction to Lead	(Notes 9 & 11)	$R_{ heta JL}$	53		
Operating and storage temperature range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

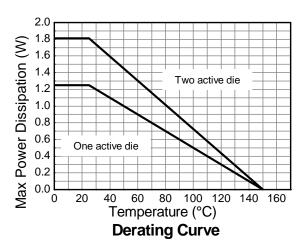
#### Notes:

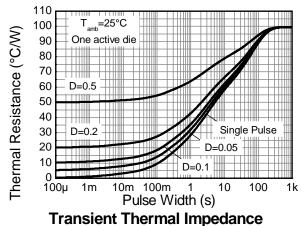
- 5. AEC-Q101  $V_{\text{GS}}$  maximum is  $\pm 16 \text{V}.$
- 6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 7. Same as note (3), except the device is measured at  $t \leq 10 \mbox{ sec.}$
- 8. Same as note (3), except the device is pulsed with D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.
- 9. For a dual device with one active die.
- 10. For a device with two active die running at equal power.
- 11. Thermal resistance from junction to solder-point (at the end of the drain lead).

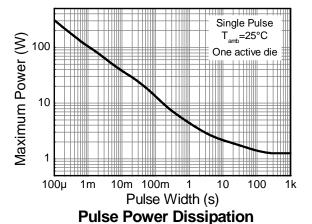


#### **Thermal Characteristics**











### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

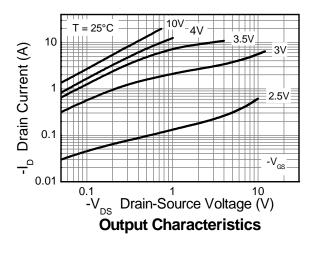
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-40	_	_	V	$I_D = -250 \mu A$ , $V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-0.5	μΑ	V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS	ON CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-1.0	_	-3.0	V	$I_D = -250 \mu A$ , $V_{DS} = V_{GS}$	
Static Drain-Source On-Resistance (Note 12)	В		0.038	0.050	Ω	$V_{GS} = -10V, I_D = -6A$	
Static Dialii-Source Off-Resistance (Note 12)	R <sub>DS(ON)</sub>	_	0.055	0.079	Ω	$V_{GS} = -4.5V, I_{D} = -5A$	
Forward Transconductance (Notes 12 & 13)	g <sub>fs</sub>	_	14	_	S	$V_{DS} = -15V, I_{D} = -6A$	
Diode Forward Voltage (Note 12)	V <sub>SD</sub>	_	-0.86	-1.2	V	$I_S = -6A, V_{GS} = 0V$	
Reverse recovery time (Note 13)	t <sub>rr</sub>		18	_	ns	-I <sub>S</sub> = -2A, di/dt = 100A/μs	
Reverse recovery charge (Note 13)	Qrr	_	12.7	_	nC		
DYNAMIC CHARACTERISTICS (Note 13)							
Input Capacitance	C <sub>iss</sub>	_	674	_	pF	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V -f = 1MHz	
Output Capacitance	Coss	_	115	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	67.7	_	pF		
Total Gate Charge (Note 14)	Qg	_	6.9	_	nC	V <sub>GS</sub> = -4.5V	
Total Gate Charge (Note 14)	Qg	_	13.9	_	nC	V <sub>DS</sub> = -20V	
Gate-Source Charge (Note 14)	$Q_{gs}$	_	2	_	nC	$V_{GS} = -10V$ $I_D = -6A$	
Gate-Drain Charge (Note 14)	Q <sub>gd</sub>	_	3.4	_	nC		
Turn-On Delay Time (Note 14)	t <sub>D(on)</sub>	_	1.9	_	ns	$V_{DD} = -20V, V_{GS} = -10V$ $I_{D} = -1A, R_{G} \approx 6.0\Omega$	
Turn-On Rise Time (Note 14)	t <sub>r</sub>	_	3.1	_	ns		
Turn-Off Delay Time (Note 14)	t <sub>D(off)</sub>	_	31.5	_	ns		
Turn-Off Fall Time (Note 14)	t <sub>f</sub>	_	12.6	_	ns		

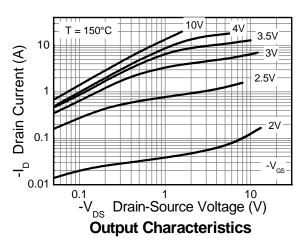
Notes:

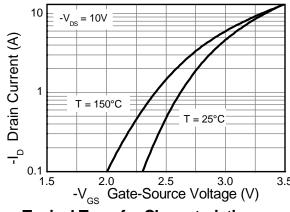
<sup>12.</sup> Measured under pulsed conditions. Pulse width  $\leq 300 \mu s$ ; duty cycle  $\leq 2\%$  13. For design aid only, not subject to production testing. 14. Switching characteristics are independent of operating junction temperatures.

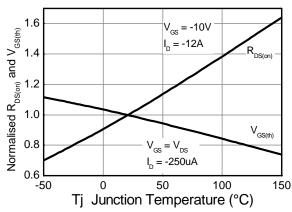


### **Typical Characteristics**



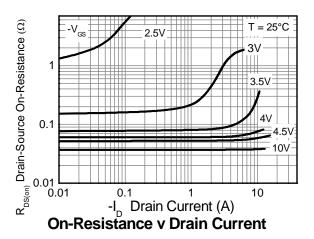


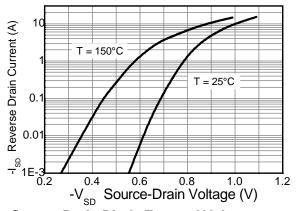




**Typical Transfer Characteristics** 



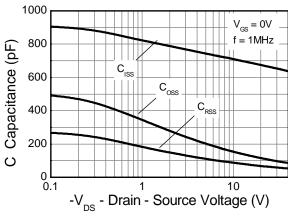




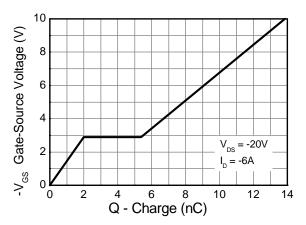
Source-Drain Diode Forward Voltage



## **Typical Characteristics – (cont.)**

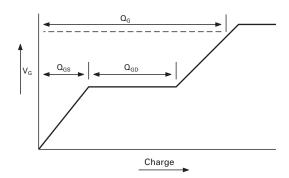


Capacitance v Drain-Source Voltage

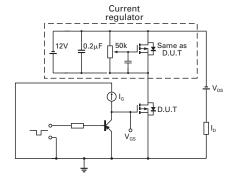


Gate-Source Voltage v Gate Charge

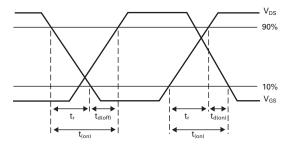
### **Test Circuits**



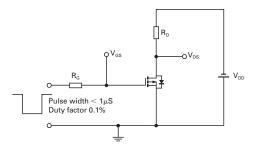
Basic gate charge waveform



Gate charge test circuit



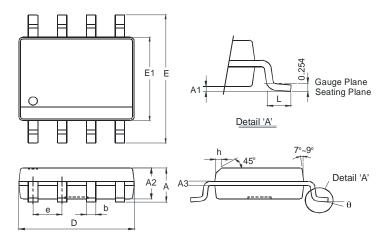
Switching time waveforms



Switching time test circuit

## **Package Outline Dimensions**

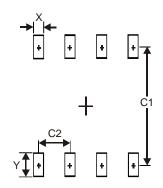
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SO-8					
Dim	Min	Max			
Α	-	1.75			
A1	0.10	0.20			
A2	1.30	1.50			
А3	0.15	0.25			
b	0.3	0.5			
D	4.85	4.95			
Е	5.90	6.10			
E1	3.85	3.95			
е	1.27 Typ				
h	-	0.35			
L	0.62	0.82			
θ	0°	8°			
All Dimensions in mm					

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.60
Υ	1.55
C1	5.4
C2	1.27





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